

What is claimed is:

1. An optical module, comprising:
 - an optical subassembly including a semiconductor optical device;
 - a substrate securing the optical subassembly and mounting a circuit for
 - 5 driving the semiconductor optical device, the circuit generating heat;
 - a base enclosing the optical subassembly, the base providing an opening for exposing the circuit;
 - a cover made of metal; and
 - a thermal block for dissipating the heat generated by the circuit, the
- 10 thermal block arranged so as to lid the opening of the base and being thermally in contact with the circuit and the cover.
2. The optical module according to claim 1, wherein the thermal block is made of metal and partitions an inner space of the base.
3. The optical module according to claim 1, further comprises a thermal sheet between the thermal block and the circuit.
- 15 4. The optical module according to claim 3, wherein the thermal sheet is made of insulator.
5. The optical module according to claim 1, further comprising a thermal sheet between the cover and the optical subassembly, the optical subassembly being thermally in contact with the cover through the thermal sheet.
- 20 6. The optical module according to claim 5, wherein the thermal sheet is made of insulator.